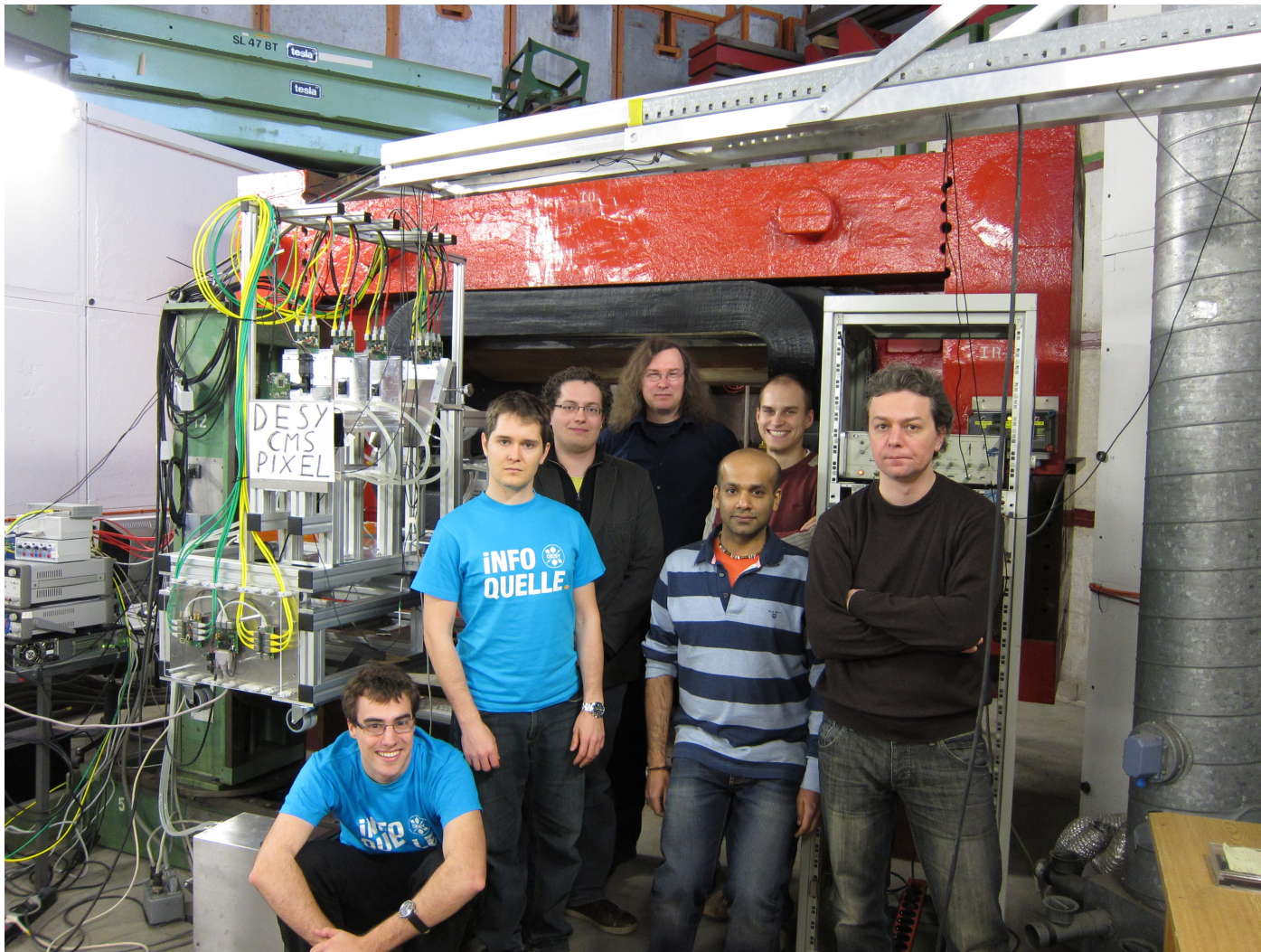


Bias scan results from the April/May 2012 beam test

Armin Burgmeier, Luigi Calligaris, Thomas Eichhorn, Shiraz Habib, Hanno Perrey, Alexey Petrukhin, Daniel Pitzl
CMS Phase I pixel upgrade, 5.10.2012



- motivated by sensor C-V curves shown 21.9.2012: drop between 130 and 150 V bias
- beam test setup
- bias scan results

2 CMS pixel planes in the telescope

3 planes
downstream

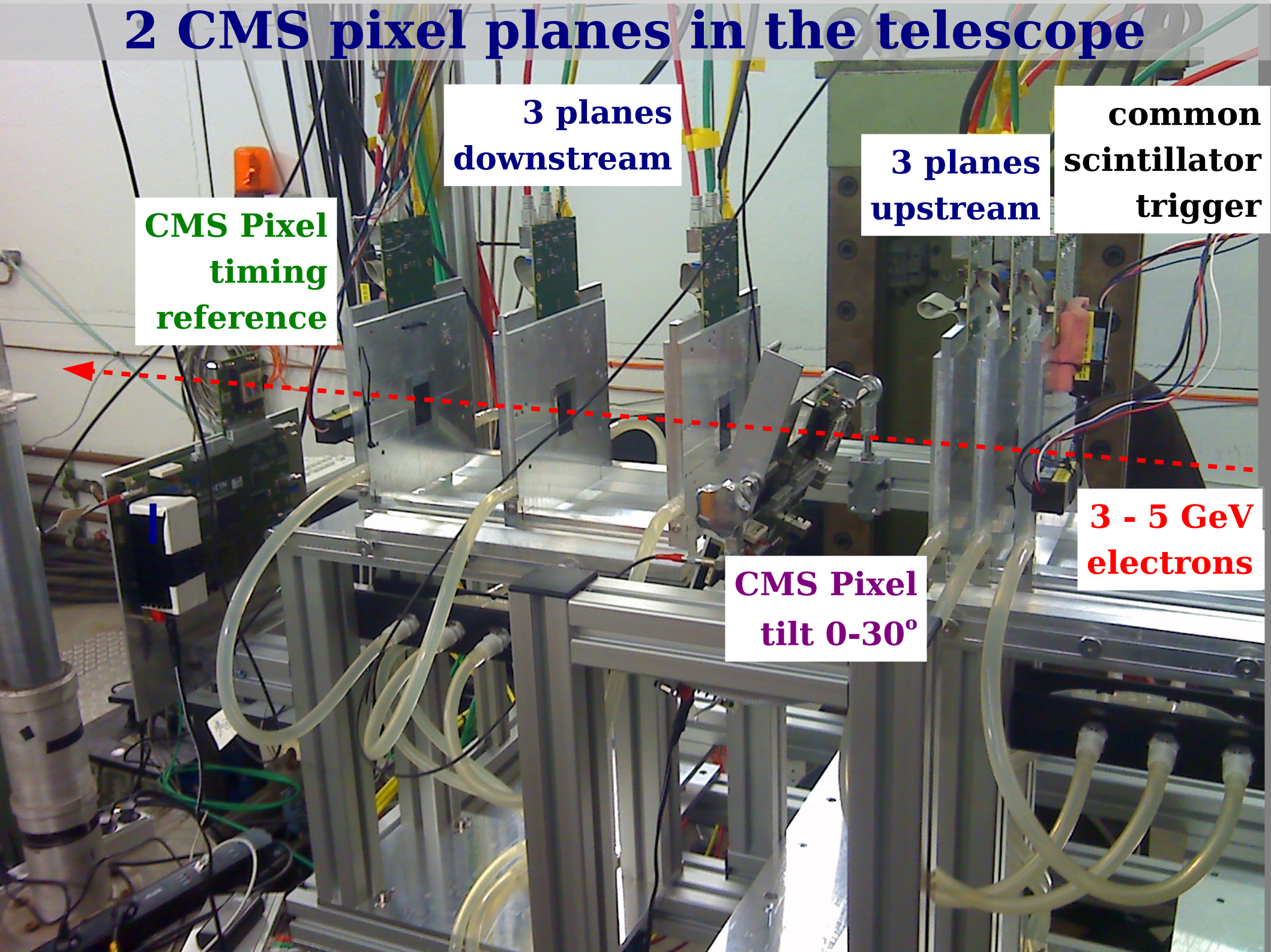
3 planes
upstream

common
scintillator
trigger

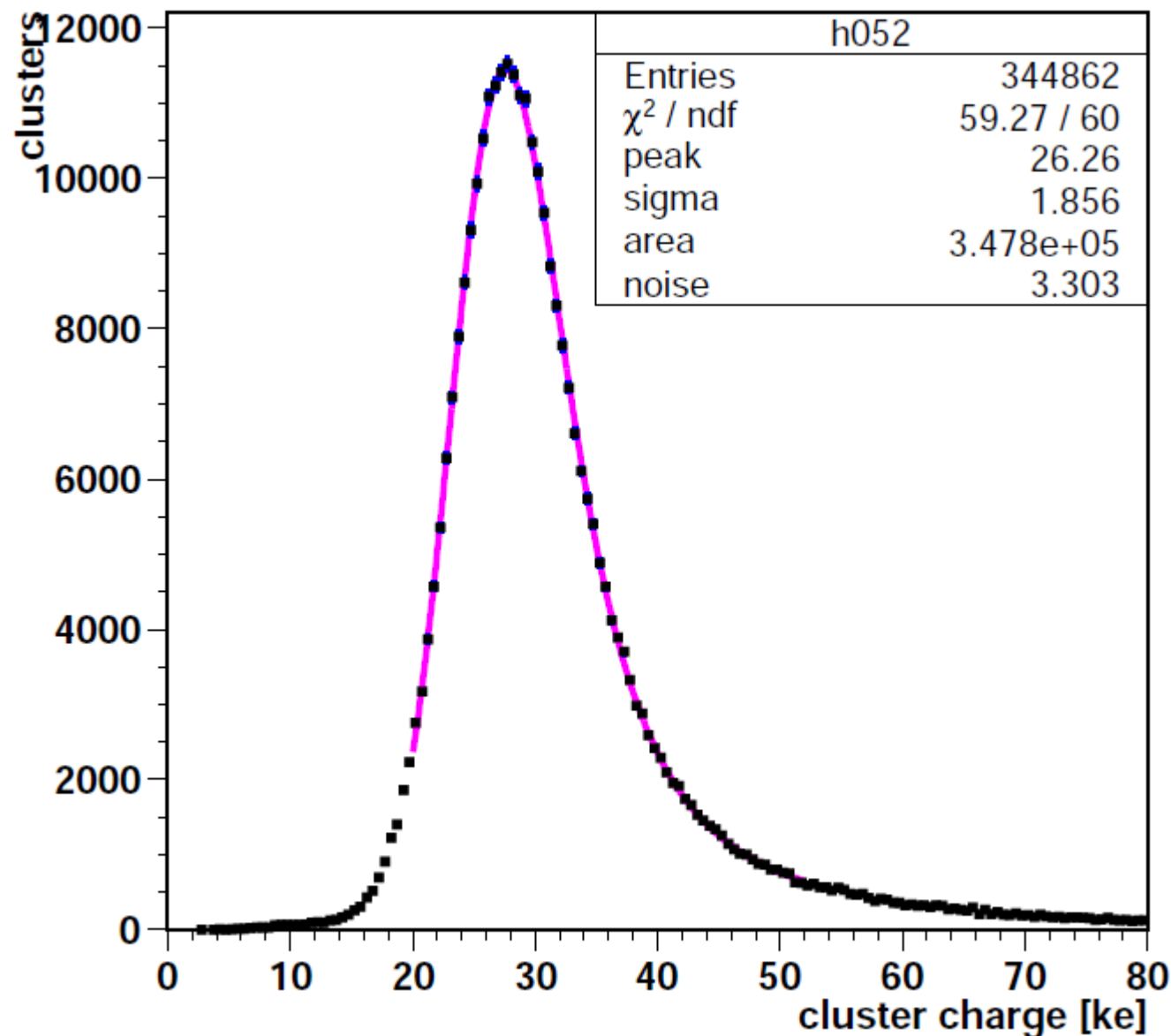
CMS Pixel
timing
reference

3 - 5 GeV
electrons

CMS Pixel
tilt 0-30°

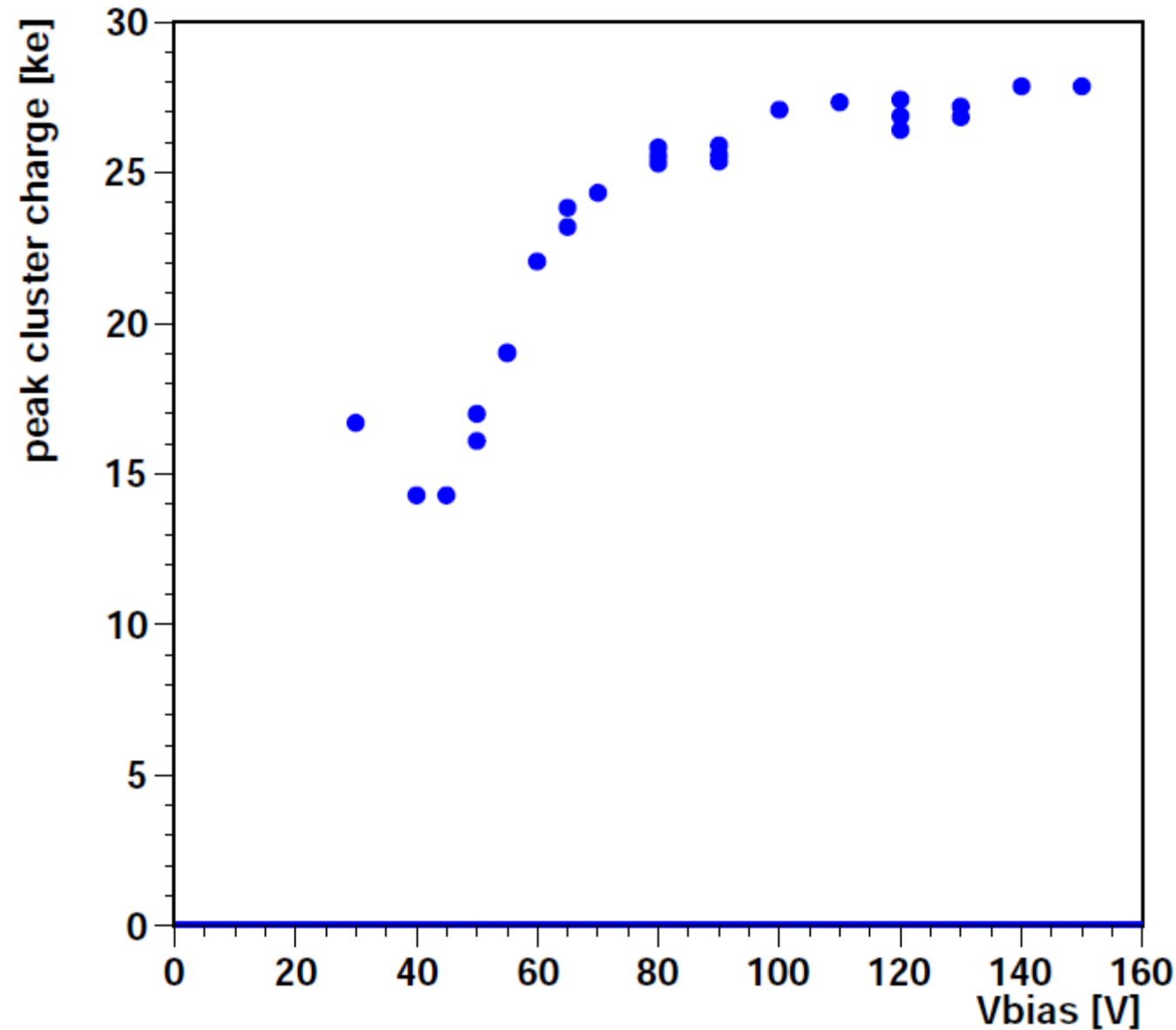


Pulse height distribution



- Chip 10 at 20° tilt.
- Gain calibration from Shiraz.
- fiducial cuts:
 - edge pixels avoided.
- Landau \otimes Gauss:
 - perfect fit,
 - peak position and width OK for 285 μm silicon,
 - Gaussian smearing too large: non-uniformities?

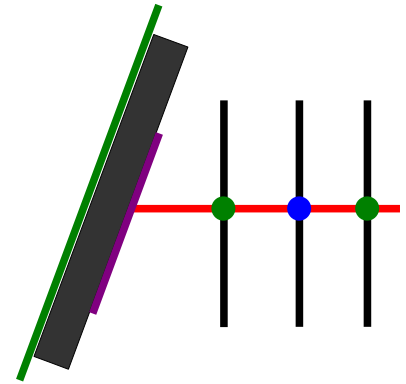
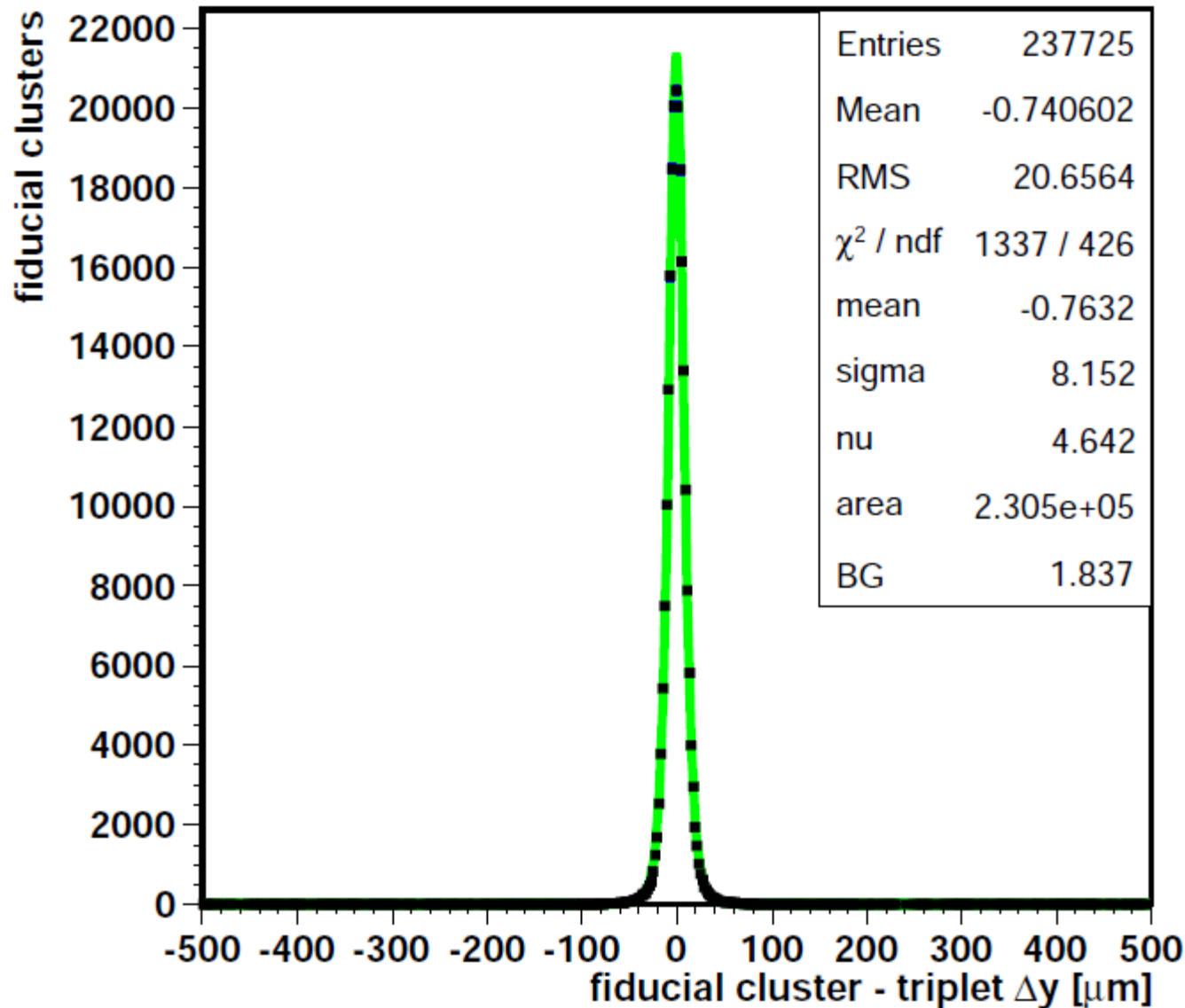
Cluster charge vs bias voltage



- Chip 10, 5.6 GeV, 20°
- Position of the Landau peak.
- slowly reaching plateau:
 - not a good indicator of full depletion

CMS pixel row resolution

run 3107, 5.6 GeV, 20° tilt



Vertical = rows

► CMS pixel = 100 μm .

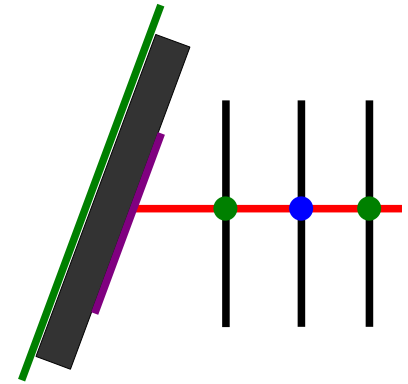
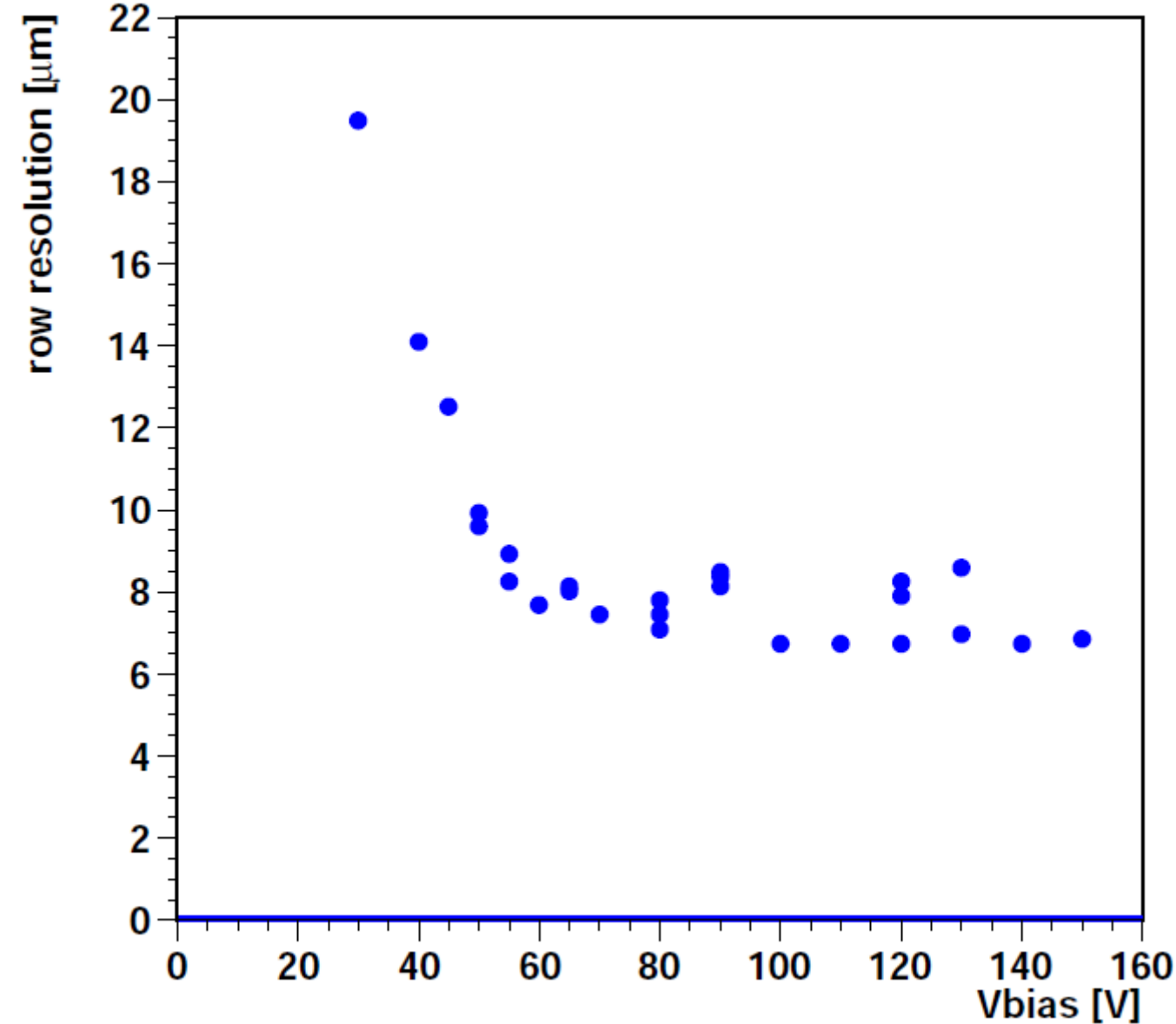
Residual:

► $\sigma = 8.2 \mu\text{m}$,

► telescope extrapolation:
4.5 μm ,

► **CMS resolution: 7 μm .**

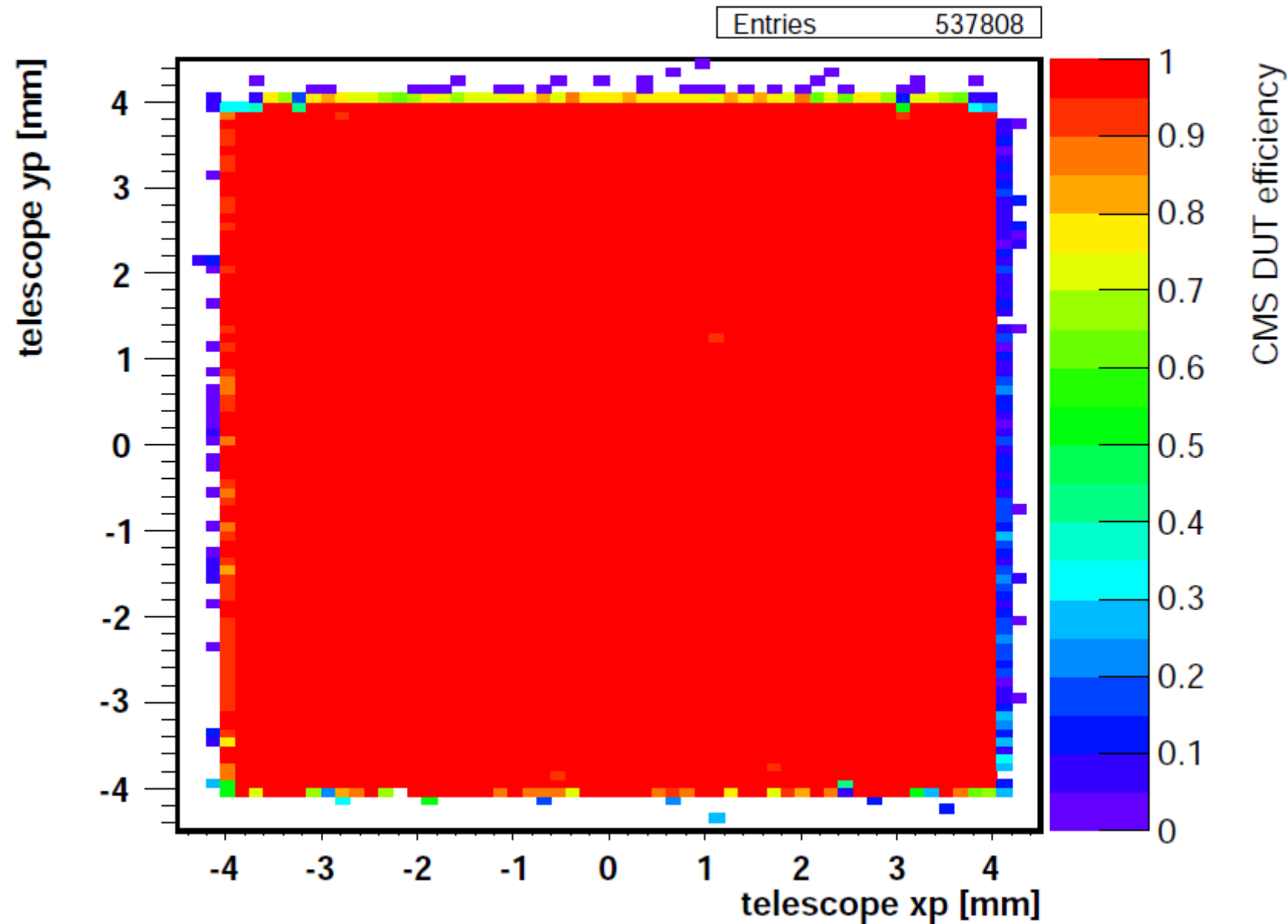
CMS pixel row resolution vs bias voltage



- Chip 10, 5.6 GeV, 20°
telescope extrapolation
uncertainty subtracted.
- best:
 - 7 μm above 80 V (full
depletion)
- outliers:
 - bad timing = worse
resolution

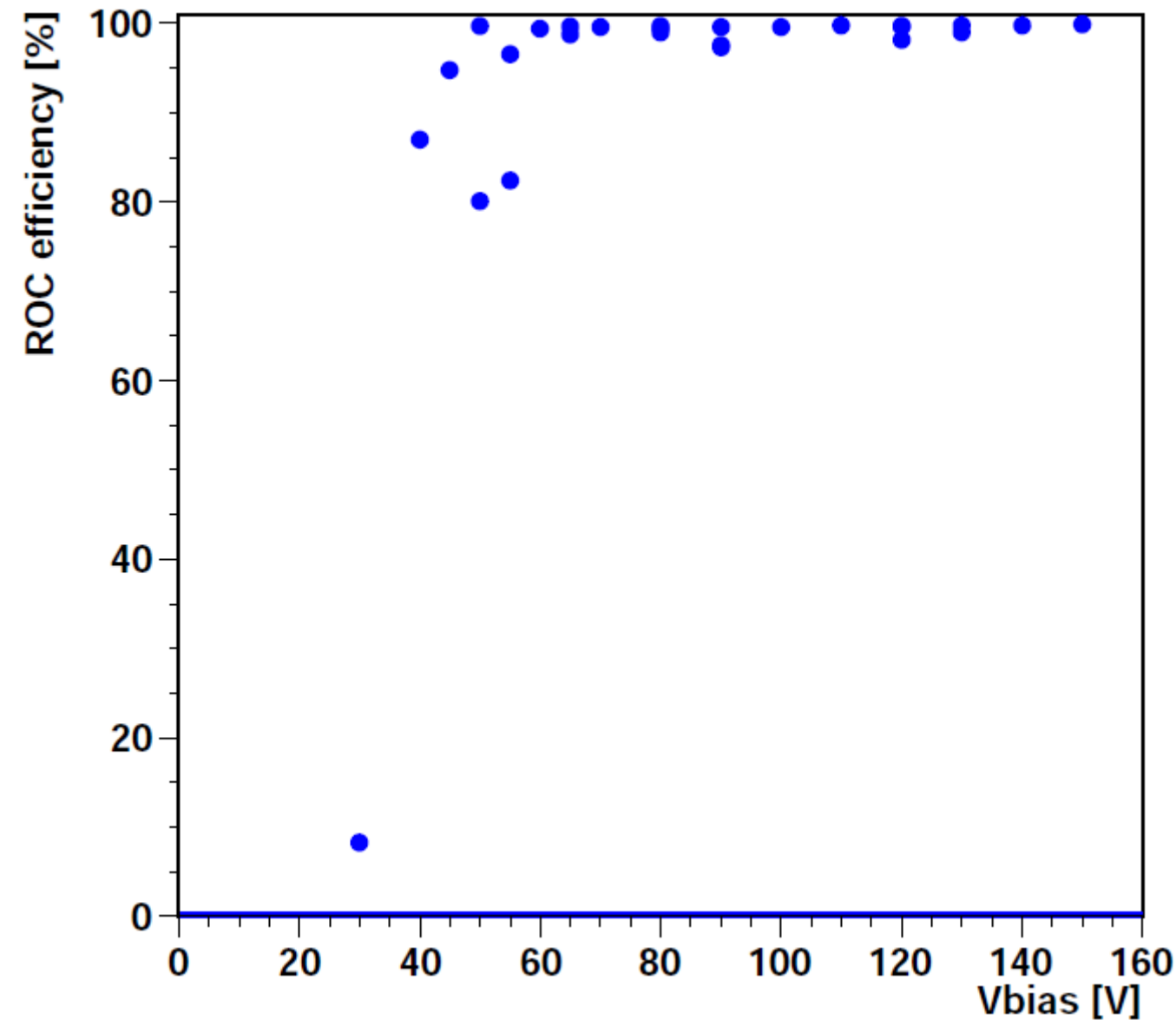
Efficiency map

efficiency = tracks with CMS hit / telescope tracks



- run 3096
- 2800 s
- 5.6 GeV
- chip 10
- tilt 20°

Efficiency vs bias voltage

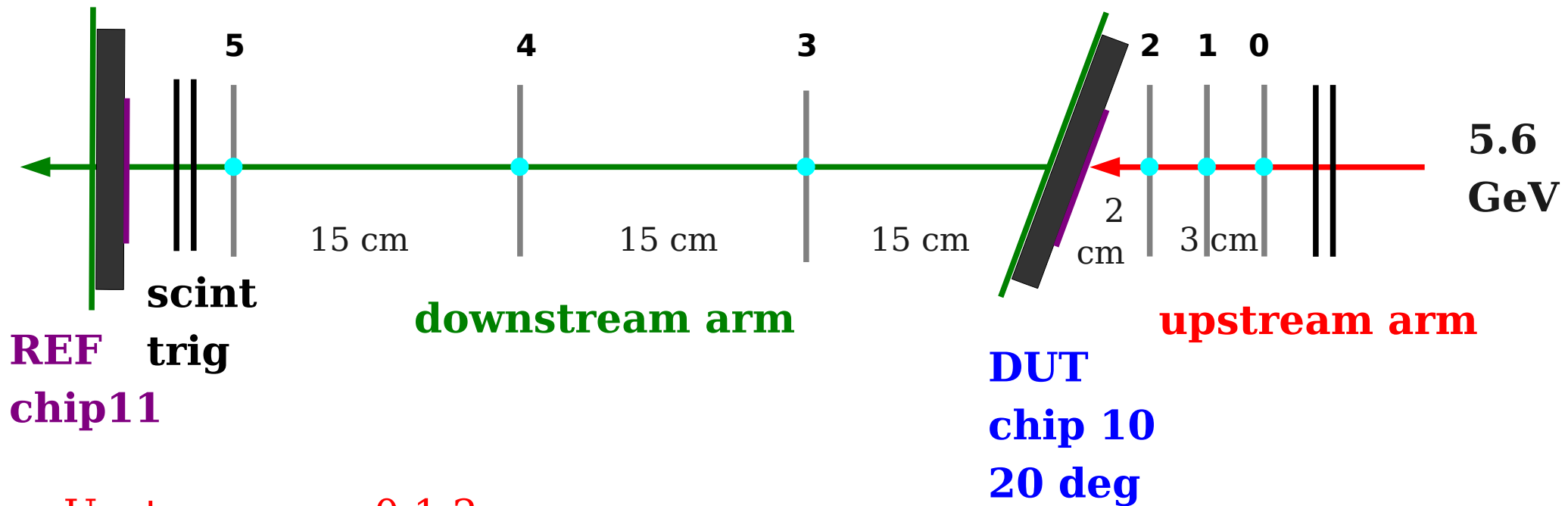


- Chip 10, 5.6 GeV, 20°
- fully efficient above 50 V: full depletion.
- some outliers with lower efficiency: timing problem.

Summary

- Beam test data with various bias voltages up to 150 V:
 - nothing special happens between 120 and 150 V:
 - in terms of resolution, efficiency, pulse height, cluster size...

Default set up



- Upstream arm 0-1-2:
 - as close as possible to DUT, but allow for tilting (open for insertion)
- DUT = single chip module, tilted by up to 30° ,
- Downstream arm 3-4-5:
 - equally spaced between DUT and REF, allow for DUT tilting
- REF = single chip module for timing, as close as possible behind scint
- trigger: 2-fold coincidence (config: TLU AndMask 12)